

REV	LOCAS	DESCRIPTION	DRAW	DATE
A0	NEW	PERLIMINARY	LITAO	2016.04.1

NOTES:

1. MATERIAL:

1.1 Housing: High Temperature Thermoplastic UL94V-0; Color Black.

1.2 Terminal: Copper Alloy.

1.3 Shell: Stainless Steel

1.4 Switch Pin: Copper Alloy

1.5 Lever: Stainless Steel

1.6 Cam: Stainless Steel

1.7 Latch: Stainless Steel

2. FINISH:

2.1 Terminal: Plated Gold on the Contact Area, Switch Area and Solder Tails, Underplated Nickel Over all.

2.2 Shell: Plated Gold on the Solder Tails, Underplated Nickel Over all.

2.3 Switch Pin: Plated Gold on the Switch Area and Solder Tails, Underplated Nickel Over all.

3. SPECIALITY:

3.1 Rated current: 0.3A

3.2 Rated voltage: 30V

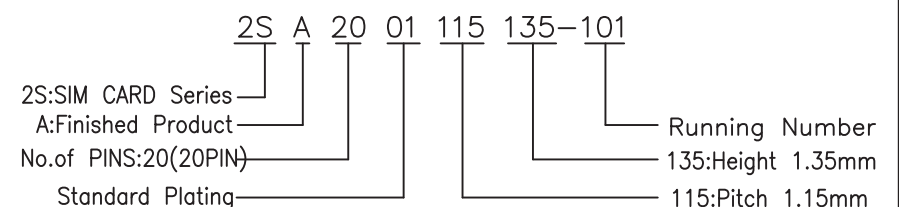
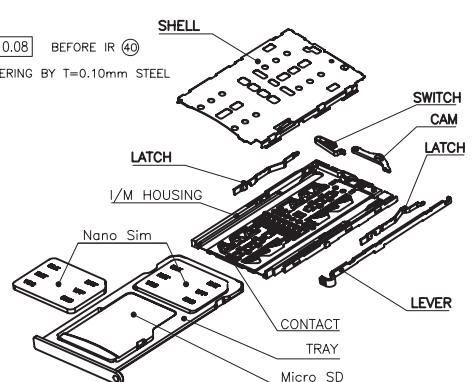
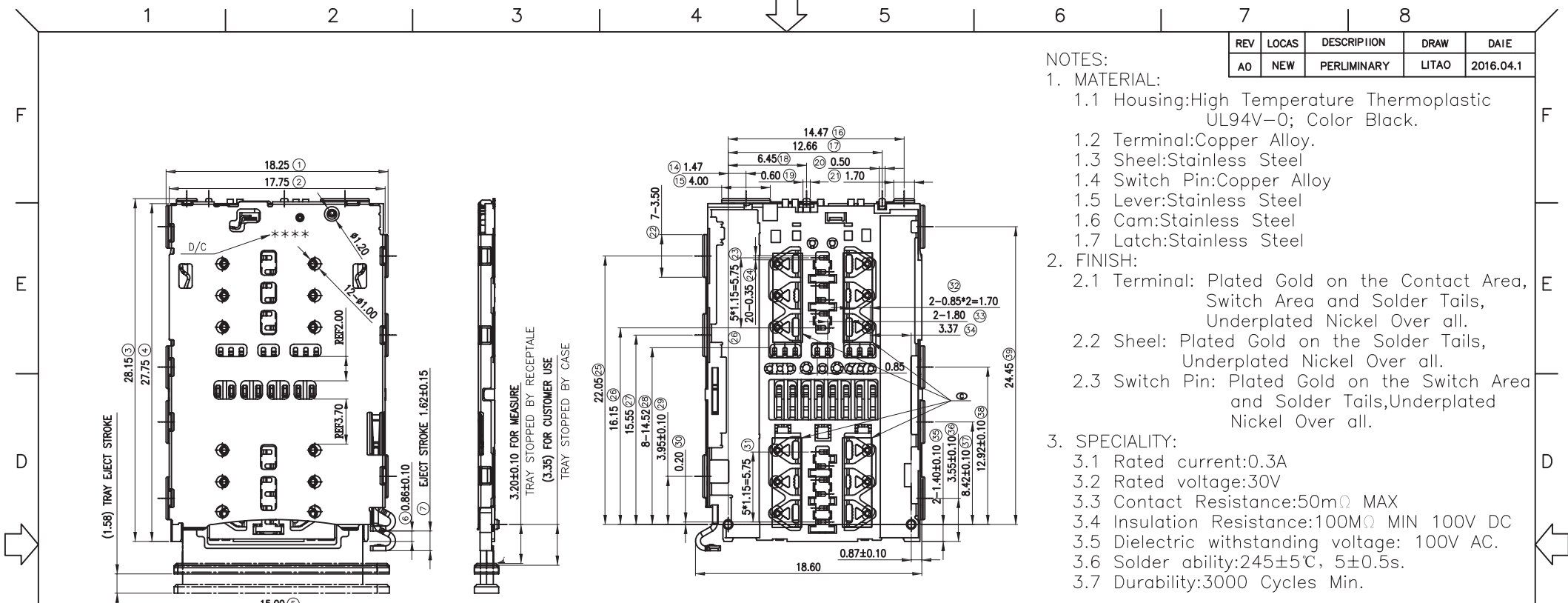
3.3 Contact Resistance: 50mΩ MAX

3.4 Insulation Resistance: 100MΩ MIN 100V DC

3.5 Dielectric withstanding voltage: 100V AC.

3.6 Solder ability: 245±5°C, 5±0.5s.

3.7 Durability: 3000 Cycles Min.



UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd,			
DECIMALS:	ANGLES:	TITLE	1.35H 3 CHOOSE 2 CARD		
X : ±0.5	X : ±2°	DWN	LITAO 2016.04.12	PART NO. 2SA2001115135-101	
X.X : ±0.3	X.X : ±1°	CHKD	SCALE 1:1	UNIT: mm	
X.XX : ±0.2		APVD	SIZE: A3	SHEET: 1 OF 3	
<b>CUSTOMER COPY</b>					

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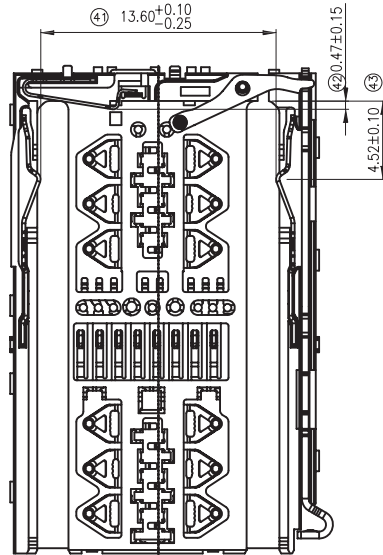
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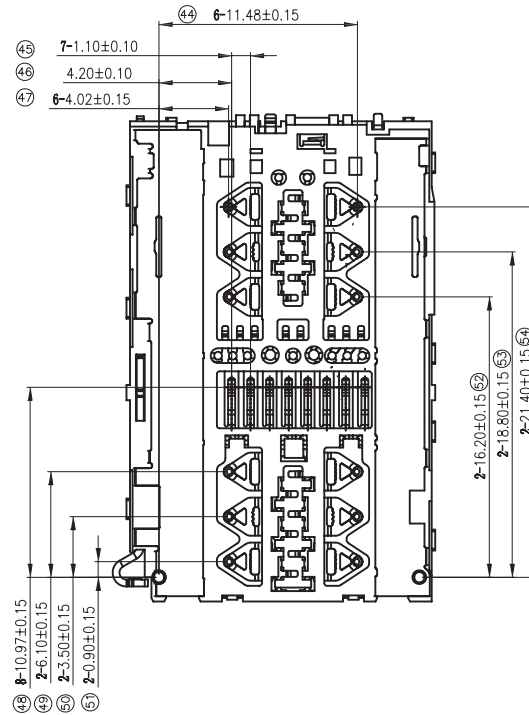
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SECTION A  
SCALE 1:1

Nano Contact N/F



SD Contact N/F

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:  
 X :±0.5 X :±2°  
 X.X :±0.3 X.X :±1°  
 X.XX :±0.2

Singatron Enterprise Co., Ltd.

TITLE	1.35H 3 CHOOSE 2 CARD		
DWN	LITAO 2016.04.12	PART NO.	2SA2001115135-101
CHKD	SCALE 1:1	UNIT: mm	④ ↗
APVD	SIZE: A3	SHEET: 2 OF 3	REV: A0

CUSTOMER COPY

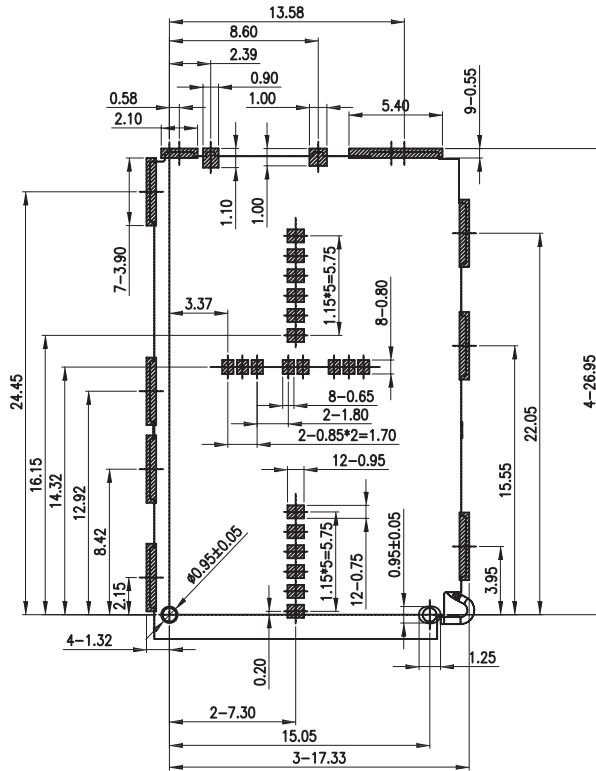
REV	LOCAS	DESCRIPTION	DRAW	DATE
A0	NEW	PERLIMINARY	LITAO	2016.04.1

CONNECTOR PIN ASSIGNMENT:

ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DATS OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
SW	TRAY DETECTION SW
S	SHELL GND
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM

CARD PIN ASSIGNMENT:

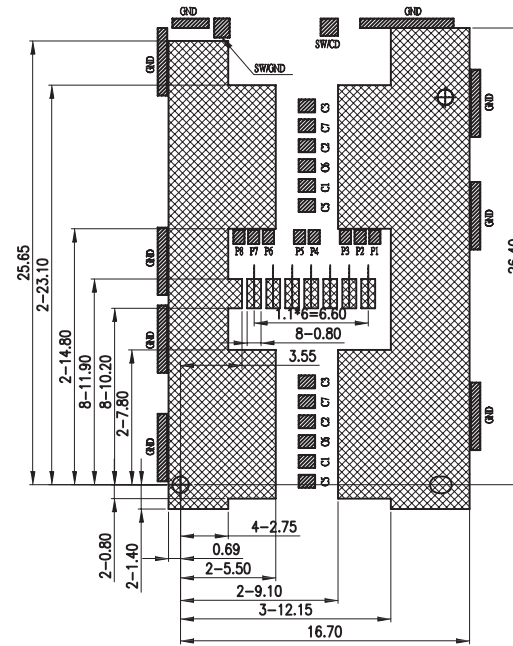
ITEM	FUNCTION
Micro SD CARD	
P1	DAT2 OF MSD
P2	CD/DATS OF MSD
P3	CMD OF MSD
P4	VDD OF MSD
P5	CLK OF MSD
P6	VSS OF MSD
P7	DAT0 OF MSD
P8	DAT1 OF MSD
NANO SIM CARD	
C1	VCC OF SIM
C2	RST OF SIM
C3	CLK OF SIM
C5	GND OF SIM
C6	VPP OF SIM
C7	DATA OF SIM



RECOMMENDED PCB LAYOUT(SOLDER AREA)  
(TOLERANCE: ±0.05)

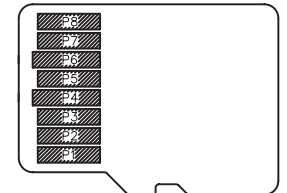
PASTE BOARD THICKNESS 0.10mm.

■ SOLDER AREA

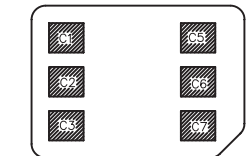


RECOMMENDED PCB LAYOUT(NO PATTERNS)  
(TOLERANCE: ±0.05)

⊠ NO PATTERNS 壹 耶 零 線

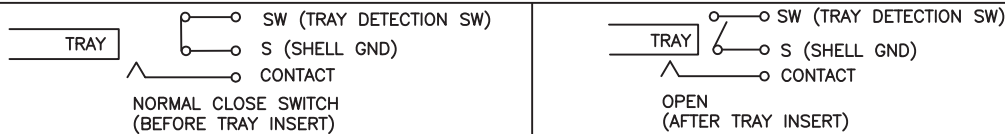


Micro SD CARD ELECTRICAL



NANO SIM CARD ELECTRICAL

CIRCUIT DIAGRAM FOR DETECT SWITCHES



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:  
X :±0.5 X :±2°  
X.X :±0.3 X.X :±1°  
X.XX :±0.2

Singatron Enterprise Co., Ltd.

TITLE	1.35H 3 CHOOSE 2 CARD		
DWN	LITAO 2016.04.12	PART NO.	2SA2001115135-101
CHKD	SCALE 1:1	UNIT:	mm
APVD	SIZE: A3	SHEET: 3 OF 3	REV: A0

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